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Assistant Commissioner For Patents,

P.O. Box 1450

Alexandria, VA 22313-1450, on December 23, 2003

Attorney for Applicant

December 23, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 1754

In re Application Of

METHOD FOR REMEDIATING

PCB CONTAMINATION ON **METAL SURFACES**

WILLIAM B. SPENCE

Serial No. 10/669,733

Filed September 24, 2003

INFORMATION DISCLOSURE STATEMENT

Eckert Seamans Cherin & Mellott, LLC U.S. Steel Tower, 600 Grant Street, 44th Floor Pittsburgh, Pennsylvania 15219 December 23, 2003

Assistant Commissioner For Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Copies of all the listed disclosures are attached hereto. citation is made solely for the purpose of giving the Patent and Trademark Office Examiner an opportunity to make an independent review of such disclosures in the course of examining this Application.

It is respectfully submitted that the present invention, as defined by the claims in the above-identified Application, is patentable over the above disclosures. No other representation of any nature is made or intended by this citation.

Respectfully submitted

David V. Radack

412.566.6777 dvr@escm.com Registration No. 33,442 Attorney For Applicant

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Substitute for form 1449A/PTO

PTO/SB/08A (08-00)

Approved for use through 10/31/2002. OMB 0651-0031

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Application Number	10/669,733				
Filing Date	September 24, 2003				
First Named Inventor	William B. Spence				
Group Art Unit	1754				
Examiner Name					
Attorney Docket Number	282258-00006				

	U.S. PATENT DOCUMENTS							
Examiner Initials*	Cite No. ¹			Number Kind Code ²		of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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FOREIGN PATENT DOCUMENTS								
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¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.



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^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.